

Lonten P-channel -30V, -4.0A, 50mΩ Power MOSFET

Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- \bullet -30V,-4.0A,R_{DS(ON).max}=50m Ω @V_{GS}=-10V
- ♦ Improved dv/dt capability
- Fast switching
- Green device available

Applications

- PWM applications
- Load switch
- Portable Equipment

Product Summary

 $\begin{array}{ll} V_{DSS} & -30V \\ R_{DS(on).max} \textcircled{0} \ V_{GS} \text{=-}10V & 50m\Omega \\ I_D & -4.0A \end{array}$

Pin Configuration





SOT-23-3

P-Channel MOSFET



Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{ t DSS}$	-30	V
Continuous drain current (T _A = 25°C)		-4.0	А
Continuous drain current (T _A = 100°C)	I _D	-2.5	A
Pulsed drain current ¹⁾	I _{DM}	-16.0	А
Gate-Source voltage	V_{GSS}	±12	V
Power Dissipation (T _A = 25°C)	P _D	1.2	W
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	$T_\mathtt{J}$	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JA}$	104	°C/W



Package Marking and Ordering Information

Device	Device Package	Marking
LPSA3481	SOT-23-3	3481

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =-250uA	-30			V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-0.6	-0.95	-1.3	V
Drain-source leakage current		V _{DS} =-30 V, V _{GS} =0 V, T _J = 25°C			-1	μΑ
	I _{DSS}	V _{DS} =-24V, V _{GS} =0 V, T _J = 125°C			-10	μΑ
Gate leakage current, Forward	I _{GSSF}	V _{GS} =12 V, V _{DS} =0 V			100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-12 V, V _{DS} =0 V			-100	nA
		V _{GS} =-10 V, I _D =-4 A		41	50	mΩ
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =-4.5 V, I _D =-3.5A		47	60	mΩ
		V _{GS} =-2.5 V, I _D =-2.5A		60	85	mΩ
Forward transconductance	g _{fs}	$V_{DS} = -5 \text{ V}$, $I_{D} = -4.0 \text{A}$		15		S
Dynamic characteristics	·			•		
Input capacitance	C _{iss}			1180		
Output capacitance	Coss	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V},$ $F = 1 \text{MHz}$		80		pF
Reverse transfer capacitance	C _{rss}	- 1 - 11/11/2		68		
Turn-on delay time	t _{d(on)}			1.8		ns
Rise time	t _r	$V_{DD} = -15V, V_{GS} = -10V, I_D = -4A,$		30.2		
Turn-off delay time	t _{d(off)}	Rg=3Ω		52.5		
Fall time	t _f			7.3		
Gate resistance	Rg	V _{GS} =0V,V _{DS} =0V,f=1MHz		11.5		Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}			2.1		
Gate to drain charge	Q_{gd}	V_{DS} =-15 V, I_{D} =-4.0A, V_{GS} =-10 V		2.3		nC
Gate charge total	Qg	- VGS10 V		19.3		
Drain-Source diode characteris	ics and Maxi	mum Ratings				
Continuous Source Current	Is				-4.0	А
Pulsed Source Current ²⁾	I _{SM}				-16.0	Α
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-2A, T _J =25℃			-1.2	V
		1		1	1	<u> </u>

Notes:

^{1:} Repetitive Rating: Pulse width limited by maximum junction temperature.

^{2:} Pulse Test: Pulse Width $\leq 300 \,\mu$ s, Duty Cycle $\leq 2\%$.



Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

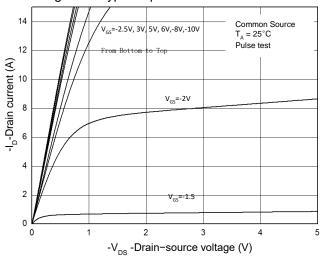


Figure 2. Transfer Characteristics

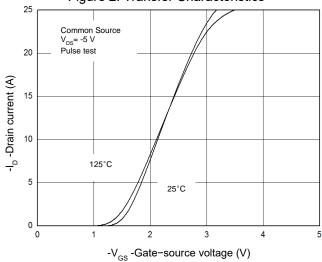


Figure 3. Capacitance Characteristics

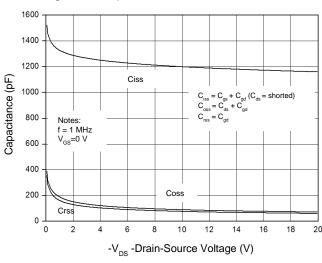


Figure 4. Gate Charge Waveform

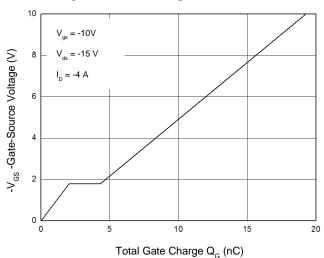


Figure 5. Body-Diode Characteristics

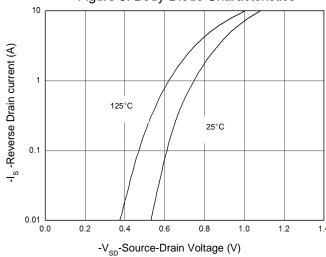
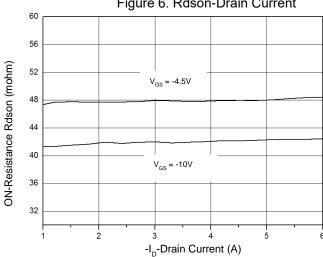


Figure 6. Rdson-Drain Current





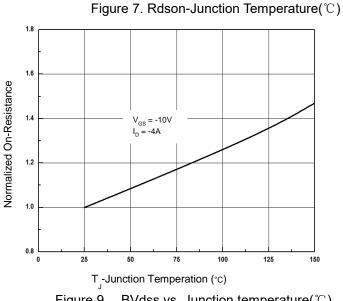


Figure 9. BVdss vs. Junction temperature(℃)

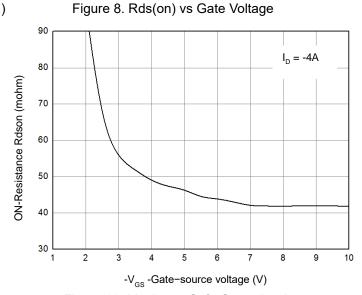
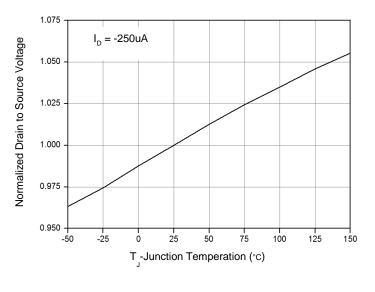


Figure 10. Maximum Safe Operating Area



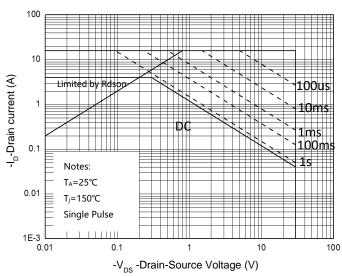
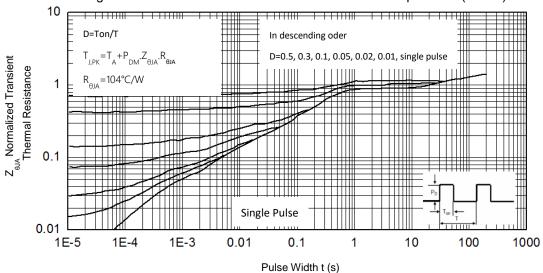


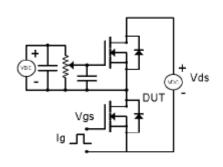
Figure 11. Normalized Maximum Transient Thermal Impedance (RthJA)





Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform



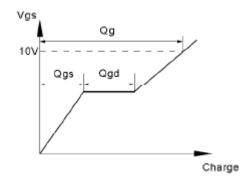
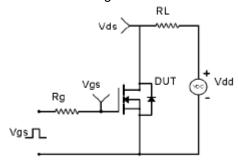


Figure 9. Resistive Switching Test Circuit & Waveforms



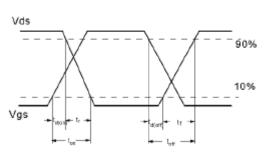
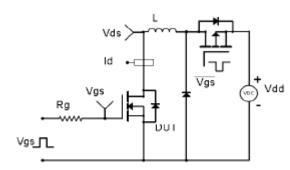


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



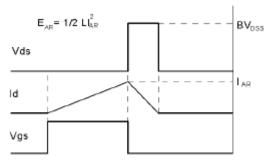
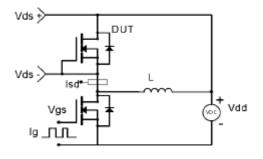
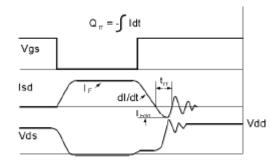


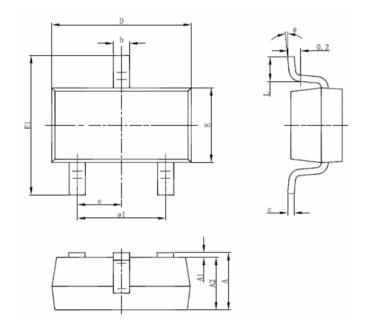
Figure 11. Diode Recovery Circuit & Waveform





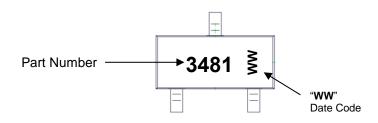


Mechanical Dimensions for SOT-23-3



COMMON DIMENSIONS					
SYMBOL	MILLIMETERS		INCHS		
	MIN	MAX	MIN	MAX	
Α	1.00	1.30	0.039	0.051	
A1	0.00	0.10	0.000	0.004	
A2	1.00	1.20	0.039	0.047	
b	0.30	0.50	0.012	0.020	
С	0.04	0.21	0.002	0.008	
D	2.80	3.00	0.110	0.118	
Е	1.50	1.70	0.059	0.067	
E1	2.60	3.00	0.102	0.118	
е	0.95 TYP.		0.037 TYP.		
e1	1.90 TYP.		0.075 TYP.		
L	0.25	0.55	0.010	0.022	
θ	0°	8°	0°	8°	

SOT-23-3 Part Marking Information





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